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Statement and signature.

the original document.

Randy W. Tung Name of Person Signing Registration No. 31,311

02-23-1999

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100971810 To the Honorable Commissioner of Paten.

uned original documents or copy thereof.

1.	Name of conveying party(ies):	Name and address of receiving party(ies):
	Chih-Lung Lin	Taiwan Semiconductor Manufacturing Co., Ltd. No. 121, Park Avenue 3 Science-Based Industrial Park Hsin-Chu, Taiwan, R.O.C.
	Additional names(s) of conveying party(ies) attached? ☐ Yes ☒ No	
3.	Nature of conveyance:	
	Assignment □ Merger	
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	Execution Date: Nov. 13, 1998	Additional name(s) & address(es) attached? □ Yes ⊠ No
4.	Application number(s) or patent number(s):	
	If this document is being filed together with a new applicatio	n, the execution date of the application is: $\underline{Nov. 13, 1998}$
	A. Patent Application No(s).	B. Patent No(s)
	09/240460	
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5.	Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
	RANDY W. TUNG Tung & Associates 838 W. Long Lake Road Bloomfield Hills, Michigan 48032	7. Total fee (37 CFR 3.41) \$40.00 ☑ Enclosed ☐ Authorized to be charged to deposit account
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To the best of my knowledge and belief/the foregoing information is true and correct and any attached copy is a true copy of

67,200-152 TSMC 1-98-304

ASSIGNMENT

WHEREAS, I, CHIH-LUNG LIN, have invented certain improvements in APPARATUS

AND METHOD FOR CONTROLLING POLISHING PROFILE IN CHEMICAL MECHANICAL

POLISHING for which I am about to make application for Letters Patent of the United States; and

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. of No. 121,

Park Avenue 3, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C, is desirous of acquiring

the entire right, title and interest in and to said invention;

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable

consideration, the receipt of which is hereby acknowledged, I, CHIH-LUNG LIN, by these

presents, do hereby sell, assign and transfer unto the said corporation and its assigns, for the territory

of the United States of America and all foreign countries, the entire right, title and interest, including

all priority rights under the International Convention associated with each country of the Union, in

and to said invention as described in the patent application executed by me on the 13th day of

Nonventer, 1998, preparatory to obtaining Letters Patent of the United States thereon,

and in and to said application and any Letters Patent that may be granted in pursuance of said

application and any divisional, continuation or continuation-in-part application thereof, and in and

to any reissue of any such patent, and in and to any patent applications which may be filed on said

invention in countries foreign to the United States and any Letters Patent granted thereon.

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REEL: 9770 FRAME: 0287

67,200-152 TSMC 1-98-304

I further authorize said corporation to apply for foreign patents on said invention in its own

name or through its designees, including subsidiaries, related companies or assignees, under the

International Convention or otherwise, and I further agree to execute all papers, including those

required for the United States and foreign applications, and to perform such other proper acts as said

corporation or its designees the rights herein assigned.

Chih-kung CHIH-LUNG LIN

TUNG & ASSOCIATES 838 W. Long Lake Road Suite 120 Bloomfield Hills, Michigan 48302

RECORDED: 02/01/1999

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PATENT REEL: 9770 FRAME: 0288